

X13 GRANDTWIN™

Multi-node Architecture with Front or Rear I/O



2U 4-Node GrandTwin™

Purpose-built Architecture for 1S

Support max DIMM, E1.S, PCIe Gen5, and CXL

- Edge to Enterprise Datacenter Deployments

Field serviceable from front/cold aisle to reduce downtime for higher availability

Flexible Front & Rear I/O config designed to help reduce cable complexities



X13SET-G-GC



SYS-211GT-HNTF (Front View)

AIOM
Ready

2U 4-Node Front I/O GrandTwin™



SYS-211GT-HNTF

SYS-211GT-HNC8F

Up to 4 U.2 NVMe/SATA drives per node

Up to 4 U.2 NVMe/SAS/SATA drives per node

2U 4-Node Rear I/O GrandTwin™



SYS-211GT-HNTR

SYS-211GT-HNC8R

Up to 6 U.2 NVMe/SATA drives per node

Up to 6 U.2 NVMe/SAS/SATA drives per node

Highly Configurable Single Processor Systems with Front or Rear I/O

GrandTwin™ is an all-new architecture purpose-built for single-processor performance. The design maximizes compute, memory and efficiency to deliver maximum density. Powered by 4th Gen Intel® Xeon® Scalable processors, GrandTwin's flexible modular design can be easily adapted for a wide range of applications, with the ability to add or remove components as required, reducing cost.

For front configurations, all I/O and node trays are fully accessible from the cold aisle, simplifying installation and servicing in space-constrained environments. Flexible storage and networking options are available via front AIOM modules, allowing countless custom configurations.

Key Applications

- MEC (Multi-Access Edge Computing)
- HPC
- Cloud Gaming
- Multi-Purpose CDN
- High-Availability Cache Cluster
- Telco Edge Cloud
- EDA (Electronic Design Automation)
- Mission-Critical Web Applications



X13 GRANDTWIN™

2U 4-Node Front I/O



2U 4-Node Front I/O



MODEL	SYS-211GT-HNTF	SYS-211GT-HNC8F
Processor Support	4th Gen Intel® Xeon® Scalable processors Single Socket LGA 4677 (Socket E) supported TDP up to 350W	4th Gen Intel® Xeon® Scalable processors Single Socket LGA 4677 (Socket E) supported TDP up to 350W
Key Applications	<ul style="list-style-type: none"> • HPC • Mission Critical Web Applications • EDA (Electric Design Automation) • Telco Edge Cloud • High-availability Cache Cluster • Multi-Purpose CDN • MEC (Multi-Access Edge Computing) • Cloud Gaming 	<ul style="list-style-type: none"> • HPC • Mission Critical Web Applications • EDA (Electric Design Automation) • Telco Edge Cloud • High-availability Cache Cluster • Multi-Purpose CDN • MEC (Multi-Access Edge Computing) • Cloud Gaming
Outstanding Features	<ul style="list-style-type: none"> • Single processor with 16 DIMM • Front I/O design • Four front access hot-swappable node in 2U • Flexible storage selection 	<ul style="list-style-type: none"> • Single processor with 16 DIMM • SAS controller built-in • Front I/O design • Four front access hot-swappable node in 2U • Flexible storage selection
Serverboard	SUPER● X13SET-G	SUPER● X13SET-GC
Chipset	Intel® C741	Intel® C741
System Memory (Max.)	16 DIMM slots UP to 4TB: 16x 256GB DRAM	16 DIMM slots UP to 4TB: 16x 256GB DRAM
Expansion Slots	2 PCIe 5.0 x16 AIOM slot(s)	2 PCIe 5.0 x16 AIOM slot(s)
Onboard Storage Controller	Intel® SATA	Broadcom® Broadcom® 3808
Connectivity	via AIOM	via AIOM
VGA/Audio	1 VGA port	1 VGA port
Management	SuperCloud Composer; SuperDoctor® 5 (SD5); Supermicro Diagnostics Offline (SDO); Supermicro Intelligent Mgmt (BMC Resources); Supermicro IPMI Utilities; Supermicro Power Manager (SPM); Supermicro Server Manager (SSM); Supermicro Server Mgmt (Redfish® API); Supermicro Thin-Agent Service (TAS); Supermicro Update Manager (SUM)	SuperCloud Composer; SuperDoctor® 5 (SD5); Supermicro Diagnostics Offline (SDO); Supermicro Intelligent Mgmt (BMC Resources); Supermicro IPMI Utilities; Supermicro Power Manager (SPM); Supermicro Server Manager (SSM); Supermicro Server Mgmt (Redfish® API); Supermicro Thin-Agent Service (TAS); Supermicro Update Manager (SUM)
Drive Bays	4x 2.5" hot-swap NVMe/SATA drive bays; 4x 2.5" NVMe dedicated; Optional RAID support via Intel® PCH	4x 2.5" hot-swap NVMe/SATA/SAS drive bays; 4x 2.5" NVMe dedicated; Optional RAID support via Broadcom® 3808 AOC
Peripheral Bays	None	None
Power Supply	Redundant 2200W Titanium level (96%)	Redundant 2200W Titanium level (96%)
Cooling System	2x 8cm heavy duty fan(s)	2x 8cm heavy duty fan(s)
Form Factor	2U Rackmount Enclosure: 449 x 88 x 711.2mm (17.67" x 3.46" x 28") Package: 626 x 248 x 1150mm (24.65" x 9.76" x 45.28")	2U Rackmount Enclosure: 449 x 88 x 711.2mm (17.67" x 3.46" x 28") Package: 626 x 248 x 1150mm (24.65" x 9.76" x 45.28")

X13 GRANDTWIN™

2U 4-Node Rear I/O

2U 4-Node Rear I/O



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